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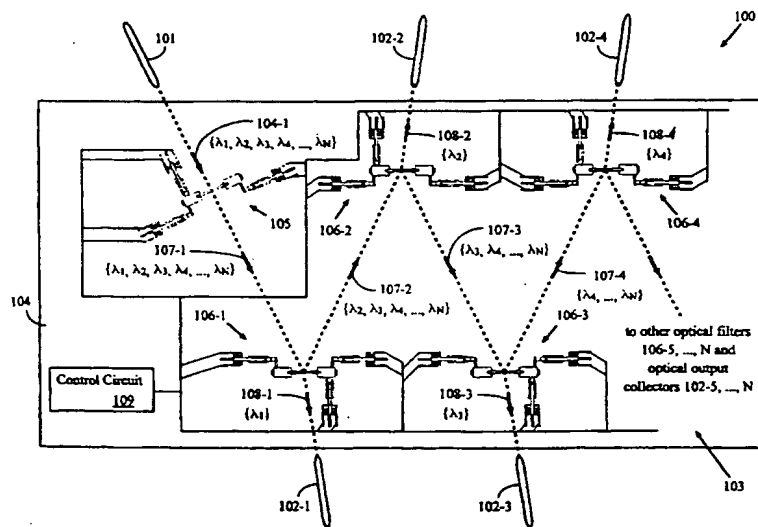
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(54) Title: MEMS OPTICAL COMPONENTS



(57) Abstract: An optical network (100), an optical device, and one or more MEMS optical components (105, 106) are disclosed. The optical network comprises one or more optical input sources (101), one or more optical output collectors (102), and the optical device. The optical device is optically coupled between the one or more optical input sources and the one or more optical output collectors. The optical device is formed on an integrated MEMS chip (104). The optical device comprises the one or more MEMS optical components formed on the integrated MEMS chip. In fact, each MEMS optical component may be monolithically fabricated on, self assemblable on, and reconfigurable or moveable on the integrated MEMS chip.

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